



**DSP 230 (Sn96.5/Ag3.5)  
LEAD FREE  
R.M.A. SOLDER PASTE**

**CORPORATE HEADQUARTERS** USA: 315 Fairbank St. Addison, IL • 630-628-8083 • FAX 630-628-6543  
**EUROPE UK:** Unit 9 Apex Ct. Bassendale Rd. Bromborough, Wirral CH62 3RE • 44 151 334 0888 • FAX 44 151 346 1408  
**ASIA-PACIFIC HEADQUARTERS** SINGAPORE: 6 Tuas South St. 5 Singapore 637790 • 65 6795 7757 • FAX 65 6795 7767  
**PHILIPPINES:** Phase 1 Qualitek Ave. Mariveles, Bataan Philippines C-2106 • 6347 935 4163 • FAX 63475613717  
**CHINA:** 3B/F, YiPa Print Bldg. 351 # JiHua Rd., Buji Shenzhen, China 518112 • 86 755 28522814 • FAX 86 755 28522787

**Description**

Delta® Solder Paste 230 is a rosin mildly activated flux system that may be used with leaded alloys as well as for high temperature lead free alloys, such as Sn96.5/Ag3.5. It provides the fluxing activity levels that promote thermal stability and prevents thermal degradation when reflowing under air atmosphere.

DSP 230 lead free solder paste exhibits superior joint strength, with excellent wettability, print definition and tack life. The post soldering residues of DSP 230 are non-conductive, non-corrosive and highly insulated.

Main Features

- Low tombstoning
- Excellent wettability
- Hard non-conductive residues

**Technical Data**

<b>Flux Classification</b>	<b>Specification</b>	<b>Test Method</b>
	ROM0	IPC-J-STD-004B
<b>Copper Mirror</b>	No removal of copper film	IPC-TM-650 2.3.32
<b>Corrosion</b>	Pass	IPC-TM-650 2.6.15
<b>SIR (cleaned)</b>	1.85 x 10 <sup>11</sup> ohms	IPC-TM-650 2.6.3.3
<b>Metal Loading</b>	89%	IPC-TM-650 2.2.20
<b>Viscosity</b>		
Malcom, poise	1650-1950	IPC-TM-650 2.4.34.3 modified
Thixotropic Index	0.50-0.60	
<b>Slump Test</b>	Pass	IPC-TM-650 2.4.35
<b>Solder Ball Test</b>	Pass	IPC-TM-650 2.4.43
<b>Tack</b>		
Initial	102 gm	JIS Z 3284
Tack retention @ 24 hr.	89 gm	JIS Z 3284
<b>Stencil Life</b>	>4 hrs	QIT 3.44.5
<b>Abandon Time</b>	30 min	QIT 3.44.6

**Physical Properties**

**Solder Composition**

Qualitek® Sn96.5/Ag3.5 is designed as a lead-free alternative for Sn/Pb alloys for electronics assembly operations. Qualitek Sn96.5/Ag3.5 alloy conforms and exceeds the impurity requirements of IPC-J-STD-006C and all other relevant international standards.

<b>Typical Analysis</b>													
<b>Sn</b>	<b>Ag</b>	<b>Cu</b>	<b>Pb</b>	<b>Sb</b>	<b>Bi</b>	<b>In</b>	<b>As</b>	<b>Fe</b>	<b>Ni</b>	<b>Cd</b>	<b>Al</b>	<b>Zn</b>	<b>Au</b>
Bal	3.0-4.0	0.080 Max	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max

	<b>Sn96.5/Ag3.5</b>
Melting Point, °C	221 E
Hardness, Brinell	15HB
Coefficient of Thermal Expansion	Pure Sn= 30.2
Tensile Strength, psi	3873
Density, g/cc	7.5
Electrical Resistivity (μohm-cm)	12.3
Electrical Conductivity, %IACS	14.0

	<b>Sn96.5/Ag3.5</b>
Yield Strength, psi	3256
Total Elongation,%	24
Joint Shear Strength, at 0.1mm/min 20 °C	27
Joint Shear Strength, at 0.1mm/min 100 °C	17
Creep Strength, N/mm <sup>2</sup> at 0.1mm/min 20 °C	13.7
Creep Strength, N/mm <sup>2</sup> at 0.1mm/min 100 °C	5
Thermal Conductivity, W/m.K	55.3

**Particle Size**

Sn96.5/Ag3.5 is available in 3(45-25μm) and 4(38-20μm) IPC-J-STD-005A powder distribution. Solder powder distribution is measured utilizing laser diffraction, optical analysis and sieve analysis. Careful control of solder powder manufacturing processes ensures the particles' shape are 95% spherical minimum (aspect ratio < 1.5) and that the alloy contains a typical maximum oxide level of 100 ppm.

**Metal Loading**

Typical metal loading for lead free DSP 230 stencil printing application is **88-89%**. Compared to typical Sn63/Sn62 solder pastes manufactured with 90% by weight metal loading, DSP 230 Lead Free provides as much as 10-12% higher metal volume than Sn63/Sn62. This increased in volume of DSP 230 promotes better wetting and spreading of Sn/Ag lead free alloy.

## **Printing of Solder Paste**

### **Stencil**

Use of chemical etched/electroformed stencil is preferred however DSP 230 has been used successfully with chemical etch, electroformed, and laser cut stencils.

### **Squeegee**

*Blades:* Metal (stainless steel) squeegee blades angled from 45-60° give the best print definition. Metal (nickel) squeegee blades angled from 45-60° give the best performance. 90-durometer polyurethane may also be used.

*Pressure:* Pressure should be adjusted at the point where the paste leaves a relatively clean stencil after each print pass. Typical pressure setting is 0.6-1.5lb per linear inch of blade.

*Speed:* Normal print speeds are 1.0-2.5 (25-50mm) per second. As print speeds increase pressure will need to be increased. Although slower print speeds are desirable, Delta Solder Paste 230 is capable of printing up to 6 inch per second.

### **Print Definition**

DSP 230 provides excellent print definition characterized by brick-like prints. Good release is seen on 12-9 mil apertures with prints speeds in the range of 1.0-6.0 inch per second (25mm-150mm).

### **Open & Abandon Time**

Tests have proven that DSP 230 will perform during continuous printing for up to 8 hrs. Field test have shown that an abandon time of at least 1 hr is possible, resulting in a perfect 1st pass print on resumption of printing.

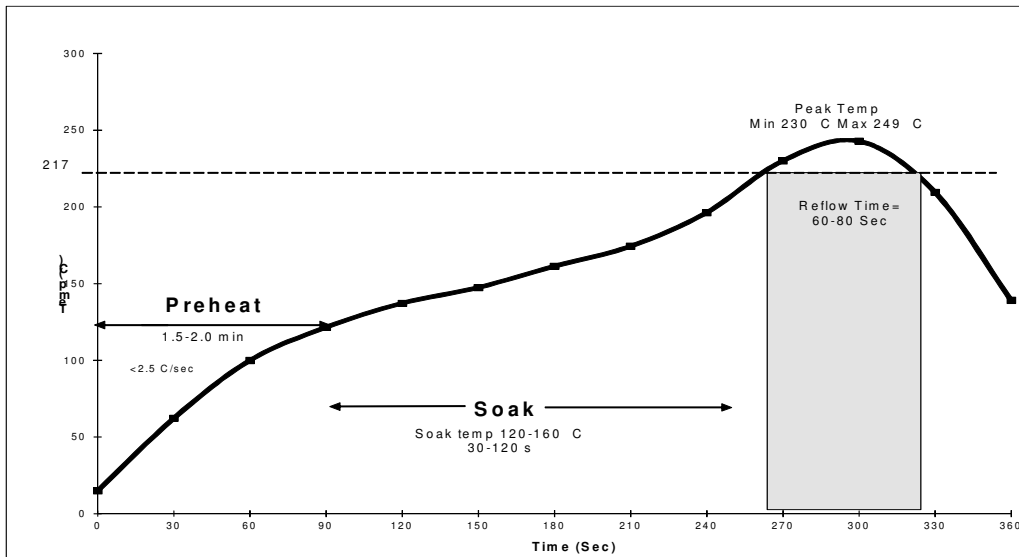
### **Paste Application**

Solder paste should be taken out of the refrigerator at least 3 to 6 hours prior to use. This will give the paste enough time to come to thermal equilibrium with the environment. Also, any fresh jar of solder paste should be gently mixed for at least one minute with a spatula. Be sure not to mix the paste too vigorously, as this will degrade the paste's viscosity characteristics and introduce entrapped air into the paste. The purpose of the mixing is to insure that the paste is smooth and consistent. If solder paste is supplied in cartridges pre-mixing is not necessary due to the shear action produced from the dispensing.

**Reflow**

Best results have been achieved when DSP 230 is reflowed in a **forced air convection** oven with a minimum of 8 zones (top & bottom), however, reflow is possible with a 4 zone oven (top & bottom).

The following is a recommended profile for a forced air convection reflow process. The melting temperature of the solder, the heat resistance of the components, and the characteristics of the PCB (i.e. density, thickness, etc.) determine the actual reflow profile.



**Preheat Zone-** The preheat zone, is also referred to as the ramp zone, and is used to elevate the temperature of the PCB to the desired soak temperature. In the preheat zone the temperature of the PCB is constantly rising, at a rate that should not exceed 2.5 C/sec. The oven's preheat zone should normally occupy 25-33% of the total heated tunnel length.

**The Soak Zone-** normally occupies 33-50% of the total heated tunnel length exposes the PCB to a relatively steady temperature that will allow the components of different mass to be uniform in temperature. The soak zone also allows the flux to concentrate and the volatiles to escape from the paste.

**The Reflow Zone-** or spike zone is to elevate the temperature of the PCB assembly from the activation temperature to the recommended peak temperature. The activation temperature is always somewhat below the melting point of the alloy, while the peak temperature is always above the melting point.

**Flux Residues & Cleaning**

DSP 230 is a Rosin Mildly Activated formulation so the residues should be removed for typical applications. We recommend using Everkleen 1005 Buffered Saponifier with a 5-15% concentration in hot 60 °C (140 °F) for residue removal.

## **Storage & Shelf Life**

It is recommended that solder paste be stored at a temperature of between 35-50 °F (2-10 °C) to minimize solvent evaporation, flux separation, and chemical activity. If room temperature storage is necessary it should be maintain between 68-77 °F (20-25 °C).

### ***Shelf Life***

Unopened Container (35-50°F/2-10°C) 6 months (from DOM)

Unopened Container (68-77°F/20-25°C) 3 months (from DOM)

## **Working Environment**

Solder paste performs best when used in a controlled environment. Maintaining ambient temperature of between 68-77 °F (20-25 °C) at a relative humidity of 40-65% will ensure consistent performance and maximum life of paste.

## **Stencil Cleaning**

Periodic cleaning of the stencil during production is recommended to prevent any paste from being deposited in unwanted areas of the board. Without stencil cleaning, solder balling will increase. We recommend a periodic dry wipe (every 5 to 10 boards) with an occasional wet wipe (every 15 to 25 boards). When running fine pitch boards, the cleaning may need to become more frequent. The wet wipes should be performed with either alcohol or a stencil cleaner. Qualitek SK-11 stencil cleaner is designed for this purpose. When cleaning the stencil at the end of a job, the cleaning should be more thorough. If you have stencil cleaning equipment, Qualitek SK- 45 Stencil Cleaner is highly recommended for stencil cleaning purposes.

## **Packaging**

6 oz. Jar	250-500 gm
6 oz. Cartridge	500-700 gm
12 oz. Cartridge	1000-1400gm

## **Disposal**

DSP 230 should be stored in a sealed container and disposed of in accordance with federal, state & local authority requirements.

Qualitek® and Delta® are registered trademarks of Qualitek International, Inc.